

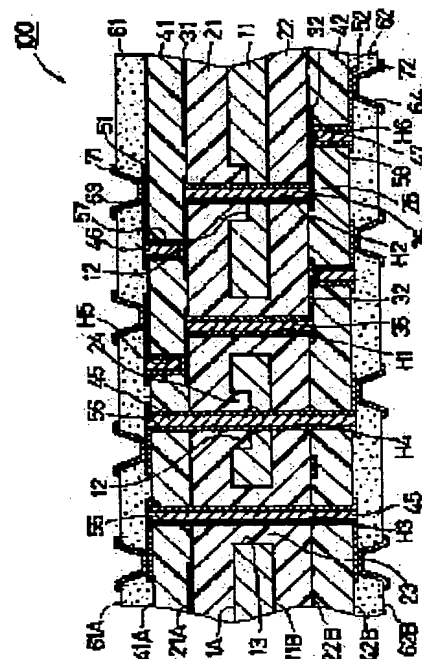
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(57) Abstract:

SOLUTION: A multilayer resin wiring board 100 is provided with a copper plate 11 having a first major surface 11A and a second major surface 11B, plural wiring layers 31, 32, 51 and 52 positioned on either of the sides, plural insulating layers 21, 22, 41 and 42 between the copper plate 11 and the wiring layers 31, 32, 51 and 52 and between the wiring layers, a copper plate connecting via 36 which connects the wiring layers 31 and 32 sandwiching the copper plate 11 and which is formed in through holes H2 and H4 for connecting the copper plate respectively passing through the copper plate 11 and a copper plate connecting via 56 which connects the wiring layers 51 and 52 and the copper plate 11. The copper plate 11 is provided with a part 12 thinner than the other part. The through holes 36 and 56 for connecting the copper plate are formed by laser treatment passing through the thinner part 12.



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